



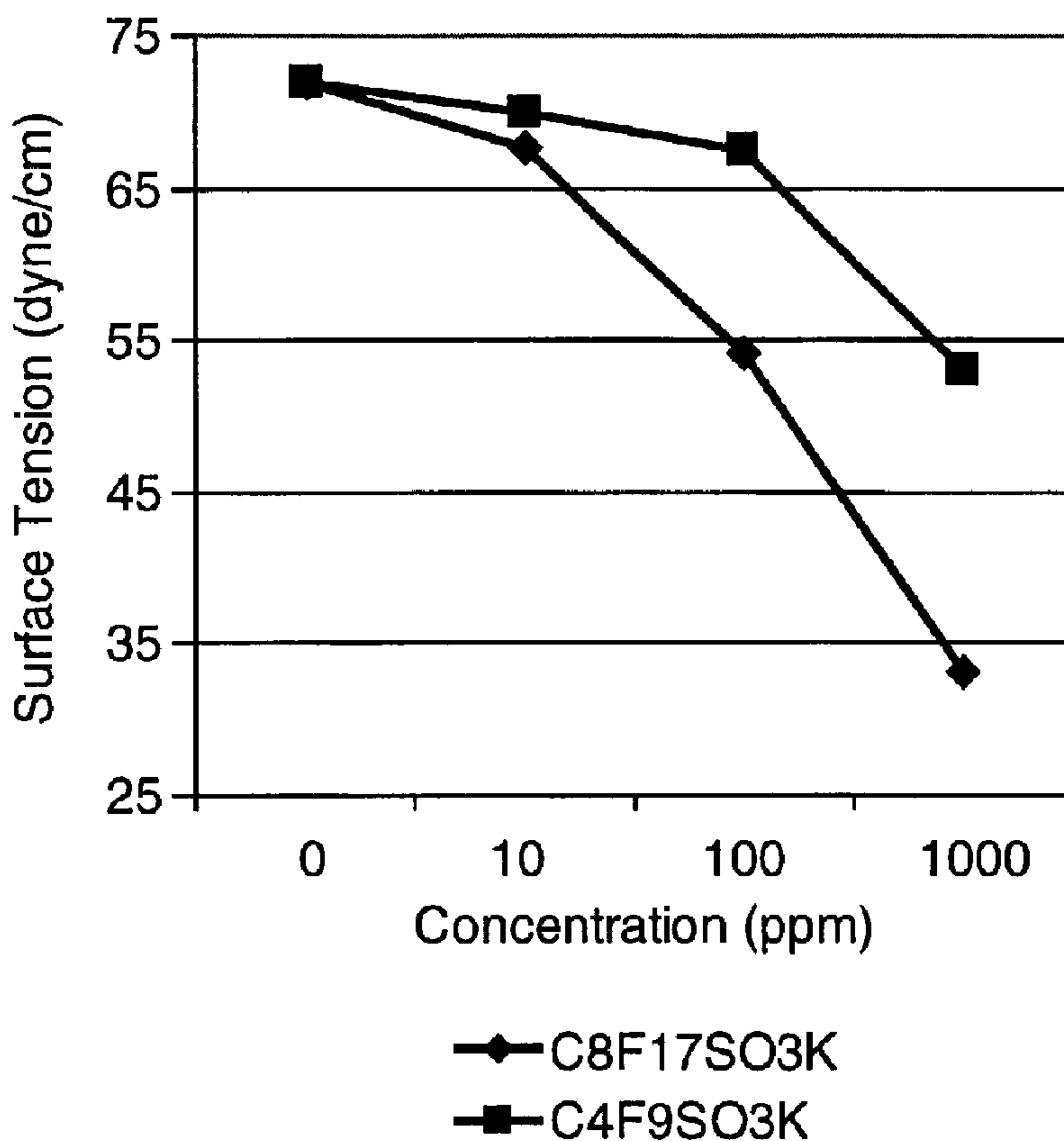
(86) Date de dépôt PCT/PCT Filing Date: 2002/03/12  
 (87) Date publication PCT/PCT Publication Date: 2002/11/21  
 (45) Date de délivrance/Issue Date: 2011/01/04  
 (85) Entrée phase nationale/National Entry: 2003/10/31  
 (86) N° demande PCT/PCT Application No.: US 2002/007844  
 (87) N° publication PCT/PCT Publication No.: 2002/092211  
 (30) Priorité/Priority: 2001/05/10 (US09/853,065)

(51) Cl.Int./Int.Cl. *B01F 17/00* (2006.01),  
*C09G 1/02* (2006.01), *C09K 13/08* (2006.01),  
*C09K 3/14* (2006.01), *C10M 105/74* (2006.01),  
*C10M 135/08* (2006.01), *C10M 135/10* (2006.01),  
*C10M 169/04* (2006.01), *C23F 1/16* (2006.01),  
*C23F 1/32* (2006.01), *C25D 3/02* (2006.01),  
*C25D 3/10* (2006.01), *C25D 3/38* (2006.01),  
*C25F 3/30* (2006.01)

(72) Inventeurs/Inventors:  
 LAMANNA, WILLIAM M., US;  
 SAVU, PATRICIA M., US;  
 PARENT, MICHAEL J., US;  
 ZAZZERA, LAWRENCE A., US

(73) Propriétaire/Owner:

(54) Titre : BIS (PERFLUOROALKANESULFONYL)IMIDES ET LEURS SELS COMME TENSIO-ACTIFS OU ADDITIFS POUR APPLICATIONS DANS DES ENVIRONNEMENTS EXTREMES, ET PROCEDES ASSOCIES  
 (54) Title: BIS (PERFLUOROALKANESULFONYL)IMIDES AND THEIR SALTS AS SURFACTANTS/ADDITIVES FOR APPLICATIONS HAVING EXTREME ENVIRONMENTS AND METHODS THEREFOR



(57) Abrégé/Abstract:

The present invention provides for the use of bis(perfluoroalkanesulfonyl)imide and its salts as surfactants or additives applications having an extreme environment.

(73) Propriétaires(suite)/Owners(continued):3M INNOVATIVE PROPERTIES COMPANY, US

(74) Agent: SMART & BIGGAR

## (12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization  
International Bureau(43) International Publication Date  
21 November 2002 (21.11.2002)

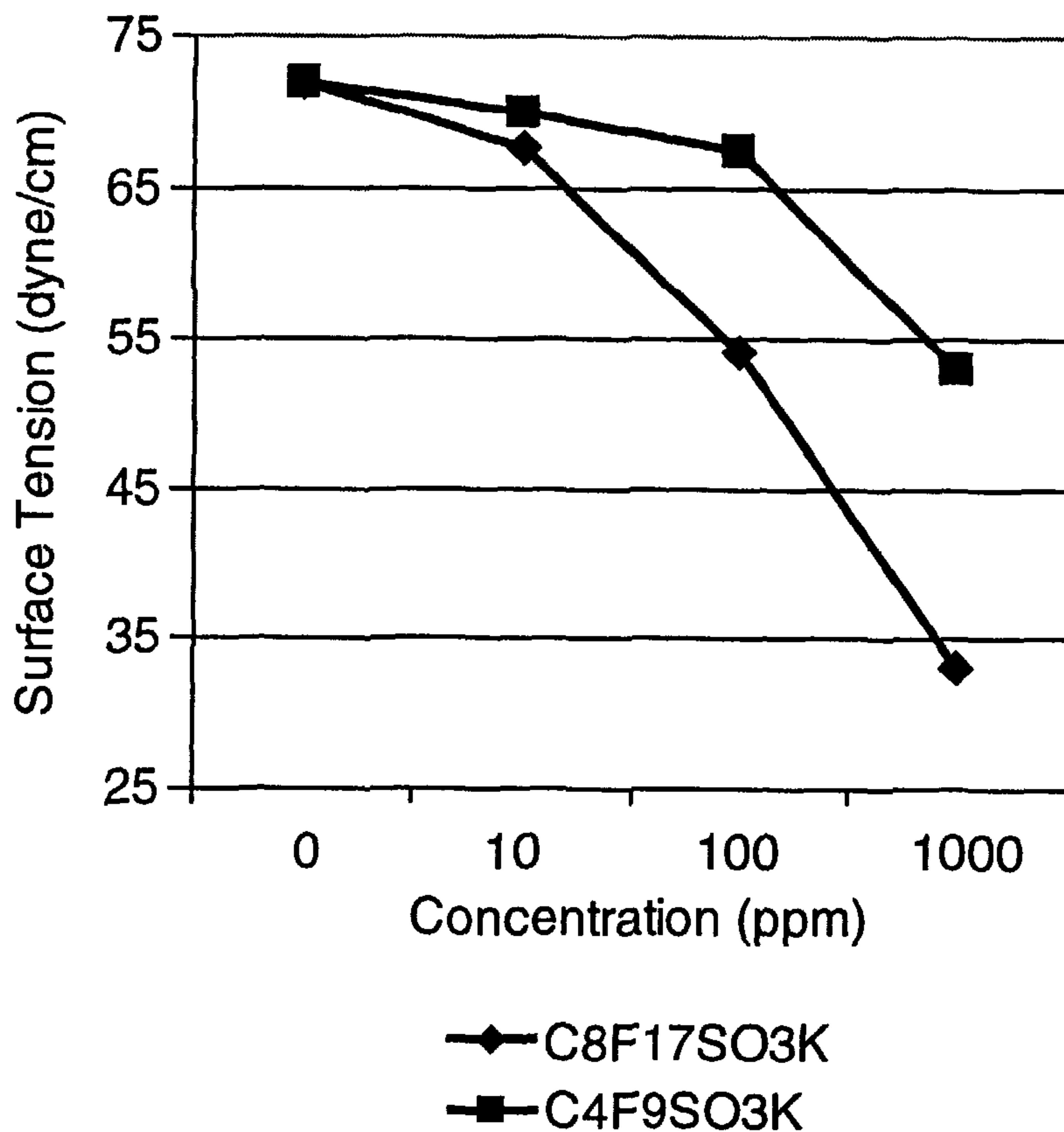
PCT

(10) International Publication Number  
WO 02/092211 A3

- (51) International Patent Classification<sup>7</sup>: **B01F 17/00**, C25F 3/30, C23F 1/16, 1/32, C25D 3/02, 3/10, C09G 1/02, C09K 3/14, C01M 169/04 // (C10M 169/04, 105:74, 135:08), C10N 30/00, 40/08
- (72) Inventors: **LAMANNA, William M.**; Post Office Box 33427, Saint Paul, MN 55133-3427 (US). **SAVU, Patricia M.**; Post Office Box 33427, Saint Paul, MN 55133-3427 (US). **PARENT, Michael J.**; Post Office Box 33427, Saint Paul, MN 55133-3427 (US). **ZAZZERA, Lawrence A.**; Post Office Box 33427, Saint Paul, MN 55133-3427 (US).
- (21) International Application Number: PCT/US02/07844
- (22) International Filing Date: 12 March 2002 (12.03.2002)
- (74) Agents: **FAGAN, Lisa M.** et al.; Office of Intellectual Property Counsel, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:  
09/853,065 10 May 2001 (10.05.2001) US
- (81) Designated States (*national*): AE, AG, AL, AM, AT (utility model), AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ (utility model), CZ, DE (utility model), DE, DK (utility model), DK, DM, DZ, EC, EE (utility model), EE, ES, FI (utility model), FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD,
- (71) Applicant: **3M INNOVATIVE PROPERTIES COMPANY** [US/US]; 3M Center, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).

[Continued on next page]

(54) Title: BIS (PERFLUOROALKANESULFONYL) IMIDES AND THEIR SALTS AS SURFACTANTS/ADDITIVES FOR APPLICATIONS HAVING EXTREME ENVIRONMENTS AND METHODS THEREFOR



(57) Abstract: The present invention provides for the use of bis(perfluoroalkanesulfonyl)imide and its salts as surfactants or additives applications having an extreme environment.

WO 02/092211 A3



SE, SG, SI, SK (utility model), SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZM, ZW.

— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations*

**(84) Designated States (regional):** ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**

— *with international search report*

**(88) Date of publication of the international search report:**

30 May 2003

**Declarations under Rule 4.17:**

— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii)) for all designations*

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

**BIS(PERFLUOROALKANESULFONYL)IMIDES AND THEIR SALTS AS  
SURFACTANTS/ADDITIVES FOR APPLICATIONS HAVING EXTREME  
ENVIRONMENTS AND METHODS THEREFOR**

5 **Field of Invention**

This invention relates to the use of bis(perfluoroalkanesulfonyl)imide and its salts as surfactants (surface active agents) or additives in aqueous and nonaqueous (or organic) solutions. More particularly, this invention relates to bis(perfluoroalkanesulfonyl)imides and their salts as surfactants or additives in solutions for applications having an extreme  
10 environment.

**Background of the Invention**

Surfactants or surface active agents are generally described as any compound that reduces surface tension when dissolved in a solution (e.g., water) or that reduces  
15 interfacial tension between two liquids or between a liquid and a solid. An additive is defined herein as any compound that when added to a base hydraulic fluid improves the erosion performance of that hydraulic fluid. The choice of surfactant/additive varies with the application, system, or solution where it is employed. Some factors that are considered when evaluating the utility of a surfactant/additive include: solubility of the  
20 surfactant/additive in the system used, pH, ultimate surface tension required for spreading and/or for leveling, how corrosive the system components are, conductivity required, and volatility of the surfactant.

Surfactants are used in a variety of applications including aqueous and non-  
aqueous (i.e., organic) solutions. Applications that involve an extreme or a harsh  
25 environment include, but are not limited to, etching solutions used in preparation of semiconductor devices, electrochemical plating and polishing solutions, wafer cleaning and polishing solutions, anisotropic etching solutions, electrolytes for alkaline batteries, and developer solutions for semiconductor manufacture. An "extreme" or "harsh"  
environment is defined as an application where a conventional hydrocarbon-based  
30 surfactant/additive would be degraded. Degradation is defined herein as protonation of an anionic surfactant or degradation or alteration (e.g., polymerization) of the chemical

structure of the surfactant that results in a change in surface tension and thus diminished surfactant performance.

Extreme environment conditions for aqueous solutions include, but are not restricted to, heat, light, radiation, oxidizing/reducing potential, high pressure, high shear, 5 high or low pH, or the presence of corrosive reagents. The pH is generally low (i.e., acidic) or high (i.e., basic). Typically, for aqueous solutions, these applications are minimally both extreme in pH and corrosive.

Extreme environment conditions for non-aqueous solutions include, but are not restricted to, high pressure, high temperature (i.e., at least 200°C), high shear, 10 environmental (trace water), or corrosive reagents, etc.

Under these conditions, most hydrocarbon surfactants either chemically or physically degrade. Thus, non-hydrocarbon-based surfactants that do not degrade in extreme environments are desirable.

Fluorocarbon surfactants such as, perfluorooctanesulfonyl fluoride (POSF) derived 15 surfactants like  $K^+OSO_2C_8F_{17}$  have been used. But these surfactants persist or ultimately degrade in the environment to other perfluorooctyl-containing compounds. It has been reported that certain perfluorooctyl-containing compounds may tend to have low bioelimination rates in living organisms. This tendency has been cited as a potential concern for some fluorochemical compounds. See, for example, U.S. Patent No. 20 5,688,884 (Baker et al.). Introduction of a surfactant and its degradation products into the environment may occur either from streams related to the use of the surfactant itself or to waste streams/emissions from its manufacture.

As a result, there is a desire for fluorine-containing compositions that are effective in providing desired surfactant properties, and that eliminate more rapidly from the body 25 (including the composition and its degradation products).

Therefore, the need exists for a surfactant or an additive that works effectively in an extreme environment application, that more rapidly eliminates from living organisms, and that can be manufactured in a cost effective manner. The precursor to these surfactants needs to be less bioaccumulative than POSF derived materials to prevent 30 potentially introducing bioaccumulative materials from manufacturing streams.

60557-7008

**Summary of the Invention**

The present invention provides bis(perfluoroalkanesulfonyl)imides and their salts as surfactants or additives in applications having extreme or harsh environments.

Advantageously, the surfactants or additives of the present invention are comprised of a  
5 perfluorinated imide anion,  $N(SO_2C_nF_{2n+1})_2$ , that is physically and chemically stable while providing outstanding surface activity under chemically harsh or extreme conditions. The surfactants or additives of the present invention furthermore do not readily protonate (even in aqueous solutions of low pH), commonly encountered in many extreme applications due to the very low basicity of the perfluorinated anion. In addition, the surfactants of the  
10 present invention can be produced from lower cost intermediates, such as  $CF_3SO_2F$  and  $C_4F_9SO_2F$ , compared to surfactants derived from  $C_8F_{17}SO_2F$  (POSF), which is produced in relatively low yields by ECF. Surprisingly, the replacement of perfluorooctanyl based surfactants with surfactants of the present invention is possible without sacrificing surface activity or surfactant performance. Moreover, the surfactants of the present invention will  
15 likely more rapidly bioeliminate.

In one aspect, the present invention comprises a method of reducing the surface tension of a solution comprising: (a) providing an aqueous solution that would degrade a hydrocarbon-based surfactant; and (b) adding to said aqueous solution a surface active agent comprising a bis(perfluoroalkanesulfonyl)imide or one of its salts.

20 Another embodiment of the present invention is a hydraulic fluid comprising: one or more phosphate esters; at least one bis(perfluoroalkanesulfonyl)imide salt additive; and optionally comprising adjuvants selected from the group consisting of viscosity index improvers, acid control components, antioxidant components, lubricants, dyes, corrosion inhibitors, antifoamers and mixtures thereof.

25 Another aspect of the present invention is an application having an extreme environment wherein said application comprises an aqueous solution comprising a bis(perfluorobutanesulfonyl)imide or one of its salts.

60557-7008

According to another aspect of the present invention, there is provided a method of reducing the surface tension of a solution comprising: i) providing an aqueous solution wherein said aqueous solution is selected  
5 from the group consisting of: (a) ammonium fluoride and hydrogen fluoride solution; (b) tetramethyl ammonium hydroxide solution; (c) an acid copper plating solution comprising copper sulfate and sulfuric acid; (d) a CMP slurry comprising abrasive particles selected from the group  
10 consisting of alumina, silica, and cerium; oxidant, etchant, and corrosion inhibitors; (e) a wafer cleaning solution comprising  $H_2O_2$ ,  $O_3$ ,  $H_2SO_4$ ,  $NH_4OH$ , or  $HCl$ , alone or in combination; (f) sodium, ammonium, or potassium hydroxide solution, quaternary ammonium hydroxides, ethylenediamine,  
15 or ethanolamine solutions; and (g) chromium trioxide, other chromium (VI) ions, and sulfuric acid; and ii) adding to said solution a surface active agent comprising a bis(perfluoroalkanesulfonyl)imide or its salts.

**Brief Description of the Drawings**

Fig. 1 is a graph of the surface tension (dyne/centimeter) versus concentration (ppm) of potassium salts of perfluorobutanesulfonate and perfluorooctanesulfonate (PFOS) in water.

5 Fig. 2 is a graph of the surface tension (dyne/centimeter) versus concentration (ppm) profile of a series of lithium salts of the imides in water.

Fig. 3 is a graph of the surface tension (dyne/centimeter) versus concentration (ppm) profile of both ammonium perfluoro-octanesulfonate (II, FC -93, available from Minnesota Mining and Manufacturing Company, St. Paul, MN.), the acid form of  
10 bis(perfluorobutanesulfonyl)imide (that when dissolved in water actually exists as a bis(perfluorobutanesulfonyl)imide anion with protonated water ( $H_3O^+$ ) as the counterion), and its salts with  $NH_4^+$ ,  $Li^+$ , and  $K^+$ .

Fig. 4 is a graph of surface tension versus concentration in the 10/1 buffered oxide etch solution for the acid form of bis(perfluorobutanesulfonyl)imide and its ammonium  
15 salt, along with a control (FC-93).

Fig. 5 is a graph of the surface tension versus concentration profiles of two JEFFAMINE™ salts of bis(perfluorobutanesulfonyl)imide and the potassium salts of bis(perfluorobutanesulfonyl)imide and the perfluoroalkanesulfonates.

20 Fig. 6 is a graph of the surface tension (dyne/centimeter) versus concentration (ppm) for the  $Mg^{2+}$ ,  $Li^+$ , and  $NH_4^+$  salts of bis(perfluorobutanesulfonyl)imide.

These figures are intended to be merely illustrative and non-limiting.

**Detailed Description of Illustrative Embodiments**

25 The present invention relates to bis(perfluoroalkanesulfonyl)imides and their salts as surfactants or additives in applications having an extreme or a harsh environment. An extreme or harsh environment having an aqueous solution is defined as some combination of conditions such as heat, light, radiation, oxidizing/reducing potential, high pressure, high shear, high (9 to 14) or low (-2 to 5) pH, or the presence of corrosive reagents that  
30 would cause conventional hydrocarbon-based surfactants or additives to degrade or protonate.

The surfactants or surface active agents (defined functionally herein as materials which concentrate at the surface of a liquid where it is dissolved or at the interface of a liquid and another immiscible liquid or solid and lower the surface tension or interfacial tension) are used in aqueous solutions in applications of the present invention. Examples  
5 of such aqueous solutions include, but are not limited to, buffered oxide etch solutions containing ammonium fluoride and hydrogen fluoride; tetramethyl ammonium hydroxide; an acidic copper plating solution comprising copper sulfate and sulfuric acid; a chemical mechanical polishing (CMP) slurry for copper comprising abrasive particles selected from the group consisting of alumina, silica, and cerium; oxidants, etchants, and corrosion  
10 inhibitors; a wafer cleaning solution comprising  $H_2O_2$ ,  $O_3$ ,  $H_2SO_4$ ,  $NH_4OH$ , or  $HCl$  alone or in combination; sodium, ammonium, or potassium hydroxide, quaternary ammonium hydroxides, ethylenediamine, or ethanolamine; and chromium trioxide; or other chromium (VI) ions, and sulfuric acid.

Furthermore, the surfactants or additives of the present invention are useful in  
15 nonaqueous (or organic) hydraulic fluids.

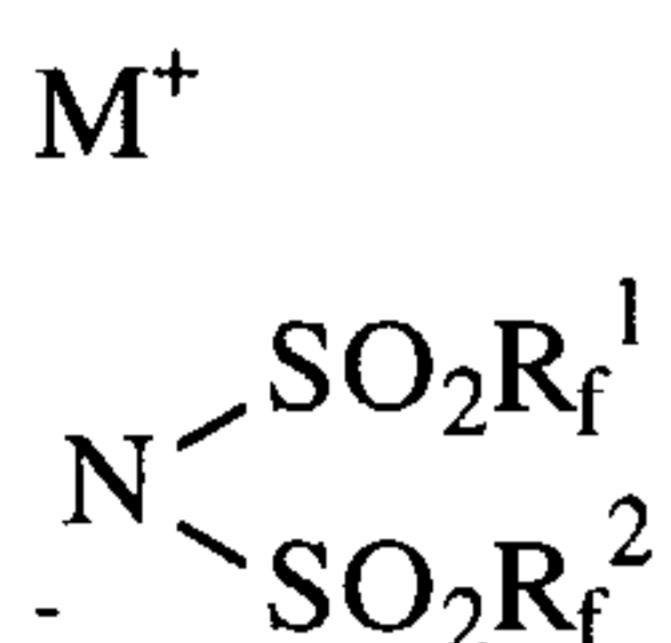
Although stable over the relatively short time frame of typical commercial applications, it is expected that the bis(perfluoroalkanesulfonyl)imide surfactants or additives of the present invention, will gradually break down to various degradation products when exposed over long time periods to biological, thermal, oxidative,  
20 hydrolytic, and photolytic conditions found in the environment. For example, compositions comprising bis(perfluorobutanesulfonyl)imide anions are expected to slowly, but ultimately degrade, to perfluorobutanesulfonate salts (i.e., salts of  $C_4F_9SO_3^-$ ). It has been surprisingly found that perfluorobutanesulfonate, tested in the form of its potassium salt, eliminates from the body more rapidly than perfluorohexanesulfonate and  
25 much more rapidly than perfluorooctanesulfonate.

One aspect of the present invention comprises a method for reducing the surface tension of an aqueous solution by adding a bis(perfluoroalkanesulfonyl)imide or its salts to the aqueous solution. The surface tension/energy is defined herein as the energy required to break or disrupt the surface of a solution. A high surface tension tends to restrain a  
30 liquid from flowing or wetting an adjacent liquid or solid substrate. Typically DuNuoy ring tensiometers or Wilhelmy plate tensiometers are used to measure surface tensions of solutions.

In another aspect, the present invention comprises an organic hydraulic fluid comprising, one or more phosphate esters, a bis(perfluoroalkanesulfonyl)imide salt additive and optionally other adjuvants or components added for optimal hydraulic fluid performance such as viscosity index improvers, acid control components, antioxidants,  
 5 lubricants, dyes, corrosion inhibitors, antifoamers and the like, and mixtures thereof.

### Surface Active Agents

The surface active agents (or surfactants) or additives of the present invention include bis(perfluoroalkanesulfonyl)imides and their salts. These imides can be  
 10 represented by the following formula:



where  $R_f^1$  and  $R_f^2$  are independently a perfluoroalkyl group containing from 1 to 12  
 15 carbon atoms, optionally containing catenated heteroatoms such as O, N, within the carbon chain. Preferably,  $R_f^1$  and  $R_f^2$  contain from 2 to 6 carbon atoms and more preferably contain from 3 to 5 carbon atoms for more rapid environmental bioelimination. M is H or an inorganic or organic cation.

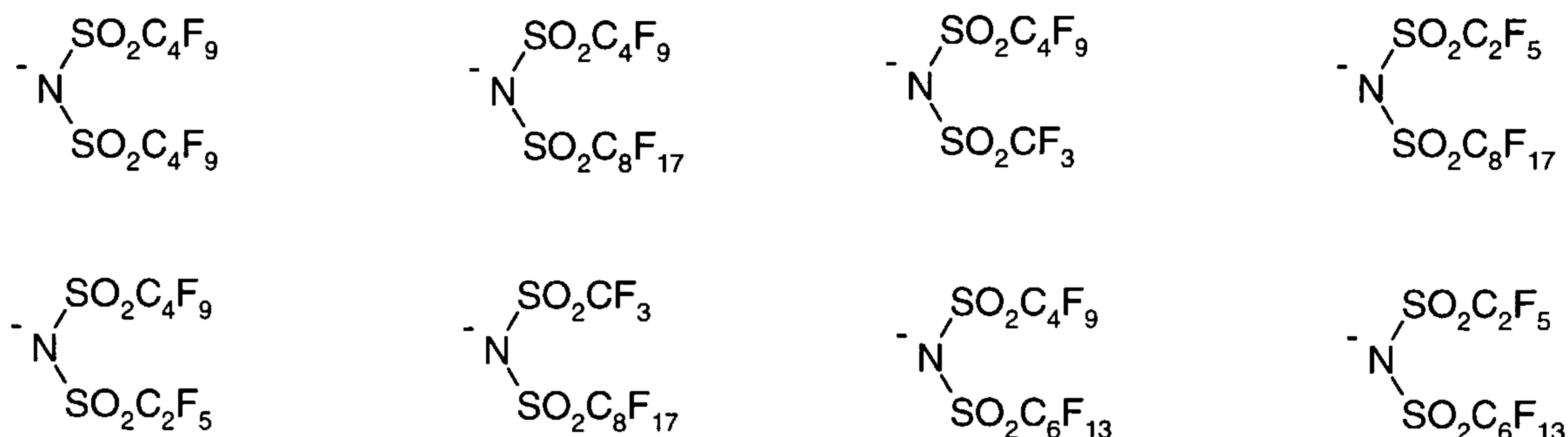
Bis(perfluorobutanesulfonyl)imide is particularly suited for these applications.

20 Bis(perfluoroalkanesulfonyl)imides and their salts may be prepared from perfluoroalkanesulfonyl halides by methods which are well known in the art and described in U.S. Patent Numbers 5,874,616, 5,723,664, and ZA 9804155. Generally, these anions can be prepared by reacting  $2R_fSO_2X$  with  $NH_3$  in the presence of  $Et_3N$  (or a similar base) or by reacting  $R_fSO_2X$  with  $R_fSO_2NH_2$  in the presence of  $Et_3N$  (or a similar base).

25 These surfactants/additives may comprise a wide variety of metallic and nonmetallic cations including, but not limited to, any alkali metal cations, any alkaline earth metal cations, (for example,  $Li^+$ ,  $K^+$ ,  $Na^+$ ,  $Ca^{2+}$ ,  $Mg^{2+}$ ),  $H^+$ ,  $H_3O^+$ ,  $NH_4^+$ ,  $Zn^{2+}$ ,  $Cu^{2+}$  and various organo-nitrogen, organo-ethers, and phosphorous onium cations (e.g., protonated forms of JEFFAMINE™ Polyalkylene Amines, available from Huntsman  
 30 Corporation, Salt Lake City, UT, and ETHOQUAD™, available from Akzo Nobel Surface Chemisity LLC., Chicago, IL.

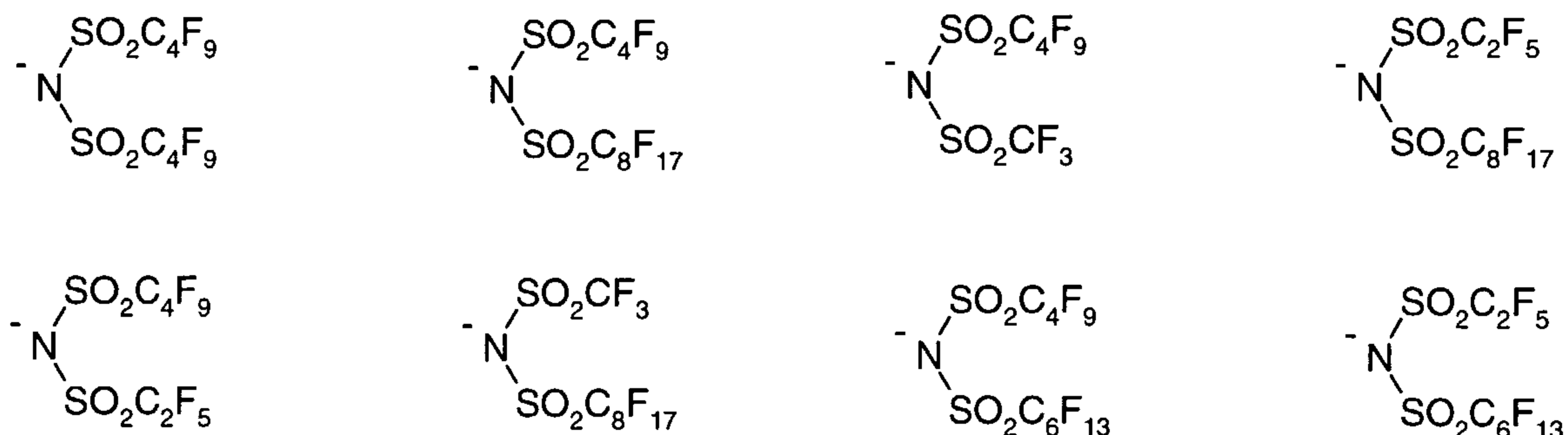
In an aqueous solution, suitable surfactants include, but are not limited to, salts having combinations of the cations  $H^+$ ,  $NH_4^+$ ,  $H_3O^+$ ,  $Na^+$ ,  $K^+$ ,  $Li^+$ ,  $Mg^{2+}$ ,  $Ca^{2+}$ ,  $Zn^{2+}$ ,  $Cu^{2+}$  and various ammonium cations derived from protonation of commercially available JEFFAMINE™ Polyalkylene Amines with any of the anions shown below:

5



In a nonaqueous, or a hydraulic fluid solution, suitable additives include, but are not limited to, salts having combinations of the cations  $Na^+$ ,  $K^+$ ,  $Mg^{2+}$ ,  $Ca^{2+}$ ,  $Me_4N^+$ ,  $Bu_4N^+$ ,  $Bu_4P^+$ , 1,3-ethylmethylimidazolium, and N-butylpyridinium with any one of the anions shown below:

10



15

Based on the art, one skilled in the art would expect that surfactants (surface active agents) or additives derived from a shorter fluorochemical chain could not be as effective as ones derived from a longer fluorochemical chain. Even in hydrocarbon surfactants, increasing the chain length of the hydrocarbon chain, decreases the CMC (critical micelle concentration). The decrease in CMC is roughly one order of magnitude for each  $-CH_2CH_2-$  added to the chain (Amphoteric Surfactants, edited by Eric G. Lomax, Marcel Dekker Inc. (1996), p.13). The same trend has been noted in surfactants derived from the perfluorocarboxylic acids and the sulfonic acids (Organofluorine Chemicals and their

Industrial Applications, edited by R. E. Banks, Ellis Horwood Ltd. (1979), p. 56; J. O. Hendrichs, *Ind. Eng Chem*, 45, 1953, p. 103; M. K. Bernett and W. A. Zisman, *J. Phys. Chem.*, 63, 1959, p. 1912. Because models to explain the actions of surfactants often invoke the monolayer of the surfactant on the air/liquid interface, one would expect the same to be true of fluorinated surfactants, and that activity of the surfactant would be closely tied to its chain length. So, for example in Figure 1, which depicts the surface tension versus concentration profiles for the potassium salts of perfluorobutanesulfonate and perfluorooctanesulfonate (PFOS), perfluorobutanesulfonate is less effective than perfluorooctanesulfonate in lowering the surface tension of water.

Expectations from the art were that the shape of the molecule would also impact its ability to act as a surface-active agent. Zisman and others have found that with long chain carboxylic acid monolayers on metal plates, the straight chain materials give lower surface energies than the branched analogs. The idealized model of how surfactants work in solutions is believed to be represented by the monolayer of polar molecules oriented on a metal surface. Based on this information, the branched material, potassium bis(perfluorobutanesulfonyl)imide, is predicted to exhibit higher surface tension values than potassium perfluorobutanesulfonate (PBSK). Figure 5, however, demonstrates that potassium bis(perfluorobutanesulfonyl)imide exhibits surface tensions significantly less than PBSK and comparable to potassium perfluorooctanesulfonate at equal concentrations.

In addition, it is particularly advantageous to use perfluorobutanesulfonyl fluoride (PBSF) as a surfactant precursor as opposed to POSF because of the higher yield of perfluorobutanesulfonyl fluoride (58%) in electrochemical fluorination over perfluorooctanesulfonyl fluoride (31%) (Preparation, Properties, and Industrial Applications of Organofluorine Compounds, edited by R. E. Banks, Ellis Horwood Ltd (1982), p.37).

Thus, PBSF derived surfactants can be produced at a lower cost per unit weight because of their higher yields and still maintain their potency as surfactants at the same weight percent.

Bis(perfluorobutanesulfonyl)imides and their salts are superior to the other lower homologues of the imide series as far as their surfactant properties are concerned. This is shown in Figure 2 where the surface tension (dynes/cm) versus concentration (ppm) profile of a series of Li salts of the imides in water is plotted. In Figure 2, MBI is  $[\text{C}_4\text{F}_9\text{SO}_2\text{N}(-)\text{SO}_2\text{CF}_3]\text{Li}$ , BETI-Li is

$C_2F_5SO_2N(-)SO_2C_2F_5]Li$ , and HQ-115 is  $Li^+N(SO_2CF_3)_2$ , available from Minnesota Mining and Manufacturing Company, St. Paul, MN. Lithium bis(perfluorobutanesulfonyl)imide exhibits significantly lower surface tensions than the shorter chain homologues, MBI-Li, BETI-Li, and HQ-115, confirming that an increase in  
5 chain length significantly contributes to lower surface tensions.

Figure 3 shows the surface tension (dynes/cm) versus concentration (ppm) profile of ammonium perfluorooctanesulfonate (II, FC-93) versus the acid form of bis(perfluorobutanesulfonyl)imide (which in water, actually exists as the hydronium ion salt  $H_3O^+N(SO_2C_4F_9)_2$ ), as well as the  $NH_4^+$ ,  $Li^+$ , and  $K^+$  salts of  
10 bis(perfluorobutanesulfonyl)imide.

In Figure 3, the non-metallic salts of bis(perfluorobutanesulfonyl)imide such as  $H_3O^+N(SO_2C_4F_9)_2$  and  $NH_4^+N(SO_2C_4F_9)_2$  are better surfactants than  $NH_4^+OSO_2C_8F_{17}$  (FC-93, available from Minnesota Mining and Manufacturing Company, St. Paul, MN.) at concentrations up to 1000 ppm. Recommended use levels for FC-93 are 100-1000 ppm in  
15 water (Technical Service Bulletin FLUORAD™ Etching Bath Additive FC-93, Issued 10/90).

Figure 4 is a graph of surface tension (dynes/cm) versus concentration (ppm) in a 10/1 buffered oxide etch solution for the acid form of bis(perfluorobutanesulfonyl)imide and its ammonium ( $NH_4^+$ ) salt. A control of FC-93 is included in the graph, but at all  
20 concentrations the FC-93 precipitated. The bis(perfluorobutanesulfonyl)imide and its salts in contrast were soluble at all the concentrations. The 1000 ppm solutions of bis(perfluorobutanesulfonyl)imide were slightly hazy to the eye.

The protonated JEFFAMINE™ salts of bis(perfluorobutanesulfonyl)imide ( $(DBI)_2$  JEFFAMINE™ ED-600 and  $(DBI)_3$ T-403) function as a surfactant. In Figure 5, the  
25 surface energies (dynes/cm) versus concentration (ppm) profiles of two JEFFAMINE™ salts of bis(perfluorobutanesulfonyl)imide, in water, are shown and compared with the potassium salts of the perfluoroalkanesulfonates. Both of the JEFFAMINE™ salts produce significantly lower surface tensions than  $C_4F_9SO_3K$ .  $(DBI)_3$  JEFFAMINE™ T-403 exhibits significantly lower surface tensions than all of the potassium salts in Figure  
30 5 ( $C_8F_{17}SO_3K$ ,  $C_4F_9SO_3K$ ,  $C_4F_9SO_2NKSO_2C_4F_9$ ) and  $(DBI)_2$  JEFFAMINE™.

The surfactants or additives of the present invention are typically added to solution in the range of 10 to 50,000 ppm, preferably 10 to 5000 ppm.

### Applications

Applications having an extreme environment that comprises an aqueous solution include, but are not limited to, etching solutions used in the preparation of semi-conductor devices, photo-resist development and stripping solutions, electrochemical plating and polishing solutions, wafer cleaning and polishing (chemical/mechanical or chemical) solutions, and anisotropic etching solutions. Each of these applications uses an aqueous solution that would degrade many hydrocarbon surfactants. For use in semiconductor processing, a surfactant must not contain metallic counter-ions. Alkali metals are referred to as mobile contaminants. Their presence causes shifts in the threshold voltage and flat-band voltage of semiconductors. This could sufficiently alter the electronic properties of the semiconductor to potentially cause shorts in the device. (D. C. Burkman, C. A. Peterson, L. A. Zazzera, and R. J. Kopp, *Microcontamination*, November, 1988). Therefore, typically ammonium salts are used.

Silicon dioxide etching with aqueous HF solutions is used to clean silicon wafers or to pattern oxide films on silicon wafers. During etching, poor wetting of the wafer surface by the acid etchant can result in air entrapment in the form of small bubbles. These bubbles can result in bridging over of the fine openings in the patterned surface, potentially creating electrical shorts in the device. Thus, a stable surface active agent is desirable that lowers the surface tension of the etching solutions used in the preparation of semi-conductor devices., and that allows uniform wetting and etching without air entrapment.

Either aqueous hydrogen fluoride (HF) or a buffered Oxide Etch (BOE) solution can be used to pattern oxide films by removing the areas of silicon dioxide unprotected by photoresist (i.e., a photoactive film) and thus exposing the silicon underneath. A typical BOE is 1 part 49 % HF and 7 parts 40 % ammonium fluoride. The BOE does not attack the photoresist. Silicon surfaces have a lower surface energy than a silicon dioxide surface. Therefore, aqueous media do not wet the exposed silicon as well as the silicon dioxide. Thus, a surfactant is desirable to aid in wetting the exposed silicon. Stability of the hydrocarbon surfactants in the HF solution used for etching is an issue. Often less stable hydrocarbon surfactants degrade to insoluble fragments that are filtered out in the continuously filtering etch bath. The consequent rise in surface tension can occur rapidly

with its attendant higher rejection rates (K. M. Shah, P. Mikkelson, W. Cummings, Semiconductor International, October, 1988).

5 A relatively low concentration (10-1000 ppm) of fluorinated surfactant is added to the aqueous HF and BOE solutions to lower the surface tension of the solution and improve wetting. Thus, the efficiency of the wafer cleaning or oxide patterning process is enhanced. The net results are extended life of the etch bath due to the stability of the surface active agent and reduced defect rates (higher defect rates are the result of air entrapment).

10 Photolithography is a process that produces a miniature image of a circuit on a silicon wafer. A photoactive film also known as photoresist or "resist" is applied to a silicon wafer to create a thin uniform film. This process is typically performed by spin coating the photoactive film. The photoactive film is then soft baked (mild heating in an oven) to drive off the coating solvents. The photoactive film is subsequently exposed to light energy projected through a patterned mask, to define a circuit or component pattern  
15 on the silicon wafer, read-write head, or other device. In a positive photoresist the light initiates a photo-reaction with a photo-acid generator producing acid, which in turn catalyzes a chemical transformation within the photoresist thereby increasing its solubility in the developer. A developer solution comprising aqueous base (e.g., tetra methyl ammonium hydroxide, TMAH) then selectively removes the lower molecular weight  
20 material and forms the desired image in the photoresist.

In some cases, manufacturing yields of microelectronic devices will decrease because the vertical walls of the photoresist pattern collapse. The high surface tension of the aqueous developer solutions can be an important contributor to the collapse of the photoresist walls in the imaged areas. Aqueous developer solutions containing a relatively  
25 low concentration (10-1000 ppm) of the fluorinated surfactants of the present invention can reduce surface tension and minimize pattern collapse as well as minimize line edge roughness (LER), while providing stability under conditions of high pH.

The surfactants and additives of the present invention are particularly useful for electrochemical plating and polishing of metal films such as copper. Copper has been  
30 identified as a preferred interconnect material for high performance microprocessor chips because of its low electrical resistivity. The transition in manufacturing to copper dual damascene requires strict control of plating and polishing of copper. Electroplating is a

preferred method for copper interconnect deposition in the manufacture of integrated circuits because of its trench filling capacity and of its relatively low cost. Copper electroplating from acidified copper sulfate is the most popular plating chemistry due to its stability and its low cost.

5           Aqueous acid copper plating solutions generally consist of three main components: 1) copper sulfate (the source of copper and is typically in the range of 0.2 – 0.6 M), 2) sulfuric acid which provides conductivity to the electrolyte (typically in the range of 1 – 2 M), and 3) various additives, including surfactants, that are typically in the 10-10,000 ppm range.

10           Chemical mechanical polishing (CMP) is used to planarize copper interconnects in the manufacture of integrated circuits because of its relatively low cost and because copper is difficult to etch using a dry plasma. A copper CMP slurry is composed of abrasive particles, oxidants, etchants, and corrosion inhibitors. Alumina based slurry in acidic solution is widely used in copper CMP. Additives are critical for the strict control  
15 required during the plating and polishing of copper. The surfactants and additives of the present invention may be used in relatively low concentrations (10-1000 ppm) in aqueous plating and polishing solutions to lower the surface tension of the solution and to improve wetting which enhances the rate and the uniformity of the plating and polishing action. The inventive surfactants and additives further provide the stability required to survive the  
20 harsh conditions typically employed in these processes, including low pH, corrosive reagents, and both reducing and oxidizing electrochemical potentials.

          The most common processing step of semiconductor chip manufacture is wafer cleaning. During wafer cleaning, oxidative cleaning steps are used to oxidize the silicon surface and to oxidize, dissolve, and remove organic contaminants. Typically, the wafer is  
25 contacted with aqueous mixtures of H<sub>2</sub>O<sub>2</sub> or O<sub>3</sub>, H<sub>2</sub>SO<sub>4</sub>, NH<sub>4</sub>OH or HCl. Etch cleaning steps remove native and deposited silicon oxide films from the silicon surface by contacting the wafer with dilute aqueous HF. Other important oxidative and etch cleaning processes in semiconductor chip manufacture include the removal of residues left behind from plasma ashing or etching of dielectric, photoresist or metals and post CMP cleaning  
30 to remove silicon oxide residues after oxide polish.

          The wafer cleaning and polishing solutions may contain relatively low concentrations (10-1000 ppm) of fluorinated surfactant of the present invention to lower

the surface tension of the solution and improve wetting. Therefore, the rate and the uniformity of the cleaning and polishing action is enhanced. Unlike most hydrocarbon-based surfactants, the fluorinated surfactants of the present invention are stable to the highly corrosive and acidic or basic reagents used in these wafer cleaning and polishing applications.

Anisotropic etching of single crystal silicon is used to fabricate trenches, channels, membranes, and diffraction gratings for integrated circuit, optical, and microelectromechanical devices. Anisotropy results because the reaction rate in the Si(100) plane is approximately 75 times faster than in the Si(111) plane. Anisotropic etching produces V-shaped grooves with side walls 54 degrees from the Si(100) surface. Etch solutions for the anisotropic etch process are generally aqueous alkaline solutions based on sodium or potassium hydroxide, quaternary ammonium hydroxides, ethylenediamine, or ethanolamine. The etch solutions may contain a relatively low concentration (10-1000 ppm) of fluorinated surfactant of the present invention to lower the surface tension of the solution and improve wetting, therefore enhancing the rate and the uniformity of the anisotropic etching action while providing stability under harsh conditions.

The potassium salt of bis(perfluorobutanesulfonyl)imide may be used in extreme applications where the presence of the potassium ion is not of concern such as chrome plating baths, conversion coatings and metal and plastic etchants. As can be seen in Figure 5, potassium bis(perfluorobutanesulfonyl)imide has the same or better surface tension in water as  $C_8F_{17}SO_3K$  (FC-95, available from Minnesota Mining and Manufacturing Company, St. Paul, MN.), through its typical use range (10-1000 ppm).

### Hydraulic Fluid

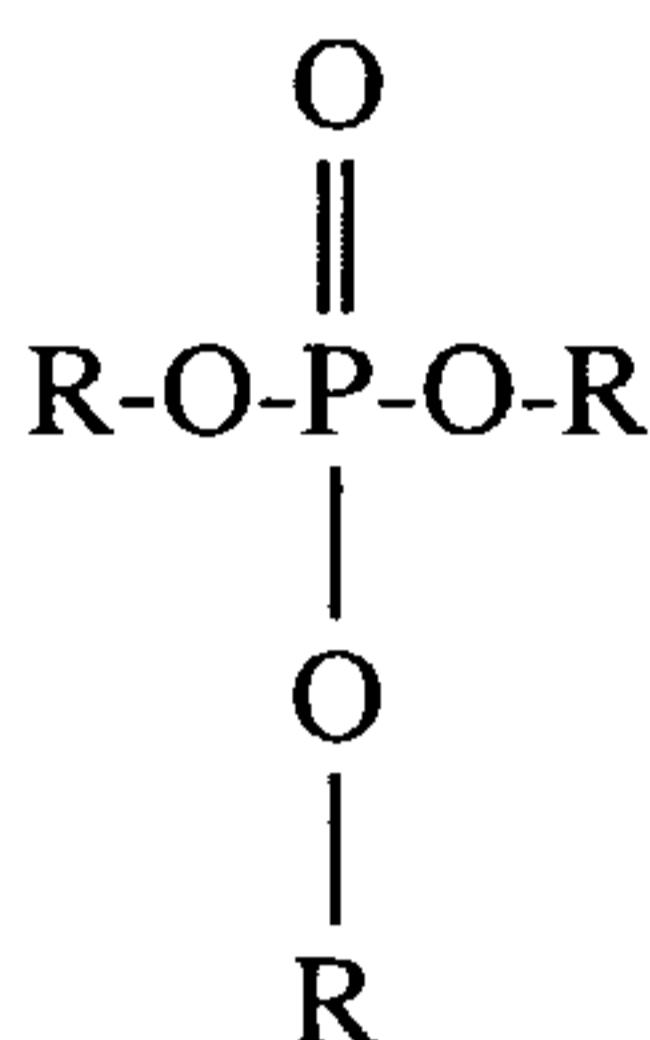
The surfactants or additives of the present invention can also be used in organic solutions such as hydraulic fluids that have an extreme environment. Suitable additives of the present invention are soluble in the base hydraulic fluid, surface active, and possess the requisite conductivity.

The potassium salts of perfluorooctanesulfonate or perfluoroethylcyclohexanesulfonate have been shown to be useful as erosion inhibitors

when dissolved in aircraft hydraulic fluids such as phosphate esters (e.g., SKYDROLS™, available from Solutia, St. Louis, MO).

The hydraulic fluids of the present invention comprise liquid phosphate esters, and mixtures thereof, wherein the phosphate esters are represented by the formula:

5



10

wherein, each R is individually an alkyl or an alkoxyalkyl group containing from 2 to 12 carbon atoms, phenyl groups and substituted phenyl groups containing up to 20 carbon atoms, wherein the substituents are alkyl, phenyl, or phenyl alkyl, and wherein the alkyl groups contain from 1 to 10 carbon atoms.

15

The hydraulic fluids comprise at least 50+% by weight of the phosphate ester. Preferably, the phosphate ester comprises from 65 to 99.999 percent by weight of the hydraulic fluid. The hydraulic fluids of this invention can also contain other lubricants, for example, polyesters, polyphenyl ethers, and the like.

20

The amount of the additive employed in the hydraulic fluid compositions of this invention is from as little as 0.001 to as much as 5.0 parts additive per 100 parts of the phosphate ester. Amounts greater than 5.0 parts can be employed if soluble in the hydraulic fluid.

25

Typically, potassium perfluoroethylcyclohexanesulfonate (FC-98, available from Minnesota Mining and Manufacturing Company, St. Paul, MN) is used commercially because of its better conductivity, improved solubility, and acceptable surface activity in phosphate esters used in commercial formulations of aircraft hydraulic fluids. In these applications, a conductivity enhancing additive is desirable for electrochemical erosion control (See e.g., WO 00/24848). The potassium salt of bis(perfluorobutanesulfonyl)imide has sufficient solubility in phosphate ester to function as an anti-erosion additive and provides high conductivity. Potassium

30

bis(perfluorobutanesulfonyl)imide dissolves in SKYDROL™ LD-4 ( a commercial aircraft hydraulic fluid manufactured by Solutia, St. Louis, MO) at up to 2 weight %.

Other adjuvants may be added to the phosphate ester such as, but not limited to, viscosity index improvers, acid control components, antioxidants, lubricants, dyes,  
5 corrosion inhibitors, antifoamers and the like.

A viscosity index improver is typically employed in the hydraulic fluids of the present invention in an amount effective to reduce the effect of temperature on the viscosity of the hydraulic fluid (typically about 2 to about 10 weight percent). Examples of suitable viscosity index improvers are disclosed, for example, in U.S. Patent No.  
10 5,464,551 and U.S. Patent No. 3,718,596. Preferred viscosity index improvers include poly(alkyl acrylate) and poly(alkyl methacrylate) esters of the type disclosed in U.S. Patent No. 3,718,596, and that are commercially available from Rohm & Haas, Philadelphia, PA.

Typically, the hydraulic fluids of the present invention further comprise an acid  
15 control component or an acid scavenger in an amount effective (typically about 4 to about 10 weight percent) to neutralize acids formed in the hydraulic fluid, such as phosphoric acid and its partial esters. Suitable acid control components are described, for example, in U.S. Patent No. 5,464,551; U.S. Patent No. 3,723,320; and U.S. Patent No. 4,206,067.

In another embodiment, the hydraulic fluids of this invention further comprise an  
20 antioxidant or mixture of antioxidants in an amount effective to inhibit oxidation of the hydraulic fluid or any of its components (typically about 0.5 to about 3 weight percent). Suitable antioxidants are described in U.S. Patent No. 5,464,551, and other hydraulic fluid patents and publications.

In yet another embodiment, the hydraulic fluids of this invention further comprise  
25 lubricants, dyes, corrosion inhibitors, antifoamers and other adjuvants or mixtures thereof to further improve the performance of the hydraulic fluid.

### **Examples**

The present invention will be further described with reference to the following  
30 non-limiting examples and test methods. All parts, percentages, and ratios are by weight unless otherwise specified.

## Test Procedures

### **Test Procedure I – Surface Tension Determination**

5 All surface tensions were determined using a Kruss K12 Tensiometer. The tensiometer was integrated with an automatic dosimat and a computer, using a software package for dynamic contact angle (K121). The program was run using a Wilhelmy platinum plate (PL12) and glass sample vessel (GL7). All parts referenced above including instrument and computer are available from Kruss USA, Charlotte, NC.

10 The comparative salts were prepared as follows:

Potassium perfluorobutanesulfonate (PBSK) FR2025 is available from Minnesota Mining and Manufacturing Company, St. Paul, MN.

15 Potassium perfluorooctanesulfonate was prepared essentially according to U.S. Patent Number 2,732,398, Example 5, with the exception that  $\text{CH}_3(\text{CH}_2)_7\text{SO}_2\text{Cl}$  is replaced with  $\text{CH}_3(\text{CH}_2)_7\text{SO}_2\text{F}$  as the starting material.

Potassium perfluoroethylcyclohexanesulfonate (FC-98) was prepared by electrochemical fluorination of  $p\text{-C}_2\text{H}_5\text{-C}_6\text{H}_4\text{-SO}_2\text{F}$  in anhydrous HF to produce  $\text{C}_2\text{F}_5\text{-C}_6\text{F}_{10}\text{-SO}_2\text{F}$  followed by hydrolysis with aqueous  $\text{K}_2\text{CO}_3$  as in U.S. Patent No. 2,732,398.

#### 20 **Example 1. Synthesis of $(\text{C}_2\text{H}_5)_3\text{NH}^+\text{N}(\text{SO}_2\text{C}_4\text{F}_9)_2$ :**

An oven-dried, 600 mL Parr reactor constructed of Hastalloy and Monel and equipped with a Magnetron stirrer, Parr 4843 controller (Parr Instrument Company, Moline, IL), a needle valve for gaseous  $\text{NH}_3$  addition, a dip tube for liquid product removal, 600 psi (4.1 MPa) pressure gauge, thermocouple probe and a heating mantle was vacuum charged with 187.2 grams anhydrous triethylamine and 362.5 grams high purity perfluorobutanesulfonyl fluoride, (available from Aldrich Chemical Company, Milwaukee, WI.). The reactor body was then chilled in a dry ice bath to approximately  $-20^\circ\text{C}$ . Once cool, the reactor was charged with 9.0 grams anhydrous ammonia gas, introduced through a needle valve attached to the reactor head assembly to allow precise gas metering from the gas cylinder mounted on an adjacent balance. Once all the ammonia was added, the reactor was mounted in its stand with a heating mantle, stirring was begun at full speed (700 RPM) and the reactor temperature was rapidly ramped to  $90^\circ\text{C}$ . A maximum

pressure of 100 psi (690 kPa) was reached at approximately 20°C during the temperature ramp. Increasing the reactor temperature beyond 40°C resulted in a rapid drop in pressure as NH<sub>3</sub> was rapidly consumed. Once the set-point temperature of 90°C was reached, the temperature was held at this value for 19 hours (overnight). At the end of the heating cycle, residual C<sub>4</sub>F<sub>9</sub>SO<sub>2</sub>F and triethylamine were removed by vacuum stripping for approximately one hour at 90°C, 40 torr through the gas port in the reactor head while stirring. Volatiles were collected in a dry ice trap. The reactor was then allowed to cool to near room temperature and the crude product collected in a polyethylene bottle by pressurizing the reactor with about 10 psi (69 kPa) nitrogen and forcing the liquid contents out the dip tube. Without disassembling or cleaning the reactor, this exact procedure was repeated a second time to generate a second batch of crude product. The combined crude product collected from batches 1 and 2 totaled 976.9 grams. Although liquid initially, the crude product partially solidifies upon standing for long periods at room temperature.

A total of 975 grams of material was melted in the oven at 50°C and was washed in a flask with 1800 grams of water at 44°C. The top water phase was removed using a TEFLON™ tube at the end of a black rubber hose attached to an aspirator, and the bottom dark brown fluorochemical phase was washed again with 1800 ml water at 57°C, then allowed to cool to 17°C at which point the stirring was stopped and the material solidified. The top water layer was then removed using a TEFLON™ tube at the end of a black rubber hose attached to an aspirator. The brown fluorochemical phase was washed with water three more times as described above. A total of 744 grams of liquid (C<sub>2</sub>H<sub>5</sub>)<sub>3</sub>NH<sup>+</sup> N(SO<sub>2</sub>C<sub>4</sub>F<sub>9</sub>)<sub>2</sub> was poured out of the flask at 77°C and weighed.

### **Example 2. Synthesis of HN(SO<sub>2</sub>C<sub>4</sub>F<sub>9</sub>)<sub>2</sub>:**

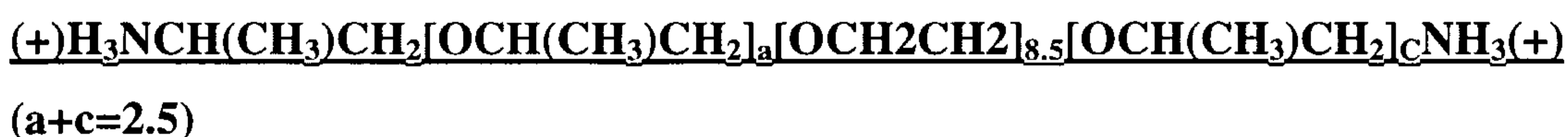
The water-washed (C<sub>2</sub>H<sub>5</sub>)<sub>3</sub>NH<sup>+</sup> salt, above was placed back in a flask and the material was heated at 10 mm Hg (1.3 kPa) vacuum at 77°C for one hour to remove the dissolved water (49 grams). At this time the vacuum was broken, and 419 grams of 94-96% sulfuric acid was added to the dried (C<sub>2</sub>H<sub>5</sub>)<sub>3</sub>NH<sup>+</sup> N(SO<sub>2</sub>C<sub>4</sub>F<sub>9</sub>)<sub>2</sub> with stirring. The temperature increased to 93°C. The acidic material was distilled from the sulfuric acid at 4 mm to give 551 grams of HN(SO<sub>2</sub>C<sub>4</sub>F<sub>9</sub>)<sub>2</sub> that distilled at 110-125°C. Water analysis revealed the product contained 4 weight % water.

**Example 3. Synthesis of  $\text{NH}_4^+\text{N}(\text{SO}_2\text{C}_4\text{F}_9)_2$** 

A total of 174 grams of  $\text{HN}(\text{SO}_2\text{C}_4\text{F}_9)_2$  from Example 2 was dissolved in 1540 grams of water. The pH of the solution was in the range of 0 to 1. A total of 17 grams of 30% ammonium hydroxide was added with stirring. The pH of the solution remained in the range of 0 to 1. An additional 6.7 grams of 30% ammonium hydroxide was added and the pH was found to be 7 to 8. This batch was heated to 40°C and nitrogen was purged through the solution for 2 hours. At that time the flask was cooled to room temperature and poured into a plastic bottle. A total of 1738 grams of  $\text{NH}_4^+\text{N}(\text{SO}_2\text{C}_4\text{F}_9)_2$  solution was isolated and found to be 9.8% solids.

**Example 4. Synthesis of  $\text{K}^+\text{N}(\text{SO}_2\text{C}_4\text{F}_9)_2$** 

A total of 58.6 grams of  $\text{HN}(\text{SO}_2\text{C}_4\text{F}_9)_2$  from Example 2 was dissolved in 250 grams of water. The pH of the solution was in the range of 0 to 1. A total of 6.9 grams of potassium carbonate was added with stirring. The batch was then heated 58 °C for 2 hours. The pH was measured to be about 6. At that time the flask was cooled to room temperature. The white solid in the flask was filtered and washed twice with 75 ml of water. After drying in the oven, a total of 47 grams of  $\text{K}^+\text{N}(\text{SO}_2\text{C}_4\text{F}_9)_2$  was isolated. The white solid remaining in the flask was washed out with repeated water washings and dried to give another 9.6 of  $\text{K}^+\text{N}(\text{SO}_2\text{C}_4\text{F}_9)_2$ .

**Example 5. Synthesis of  $[\text{N}(\text{SO}_2\text{C}_4\text{F}_9)_2]_2$** 

A total of 760 grams (MW=581, 1.26 moles, as prepared in Example 2) of  $\text{HN}(\text{SO}_2\text{C}_4\text{F}_9)_2$  which was 96% active and 4% water, was dissolved in 760 grams of hplc grade water in a 3 liter flask fitted with an overhead stirrer, thermocouple, and addition funnel. While stirring, 398 grams of JEFFAMINE™ XJT-500 (MW 600, 0.66 moles), available from Huntsman Corporation, Salt Lake City, UT., was added to the batch at 70°C over a 30 minute period. The batch was stirred for an additional 15 minutes and the pH was measured to be in the range of 7 to 8. The batch set point was set at 70°C and fitted with an overhead distillation apparatus. Vacuum was slowly pulled down on the batch via the receiver. The receiver had been precooled to -78°C. Water was stripped to

the receiver until the vacuum reached 13 mm Hg (1.7 kPa). The batch was held at 70°C and 13 mm Hg (1.7 kPa) for an hour. The amber honey-like liquid was poured out into jars and weighed. A total of 1042 grams of material was isolated.

5 Table 1 details the surface energy versus concentration profile for this material along with comparative perfluoroalkanesulfonate materials (DBI)2 JEFFAMINE™ ED600.

**Example 6. Synthesis of**

**CH<sub>3</sub>CH<sub>2</sub>C[CH<sub>2</sub>(OCH<sub>2</sub>CH(CH<sub>3</sub>))<sub>x</sub>NH<sub>3</sub><sup>+</sup>][CH<sub>2</sub>(OCH<sub>2</sub>CH(CH<sub>3</sub>))<sub>y</sub>NH<sub>3</sub><sup>+</sup>][CH<sub>2</sub>(OCH<sub>2</sub>CH(CH<sub>3</sub>))<sub>z</sub>NH<sub>3</sub><sup>+</sup>][N(SO<sub>2</sub>C<sub>4</sub>F<sub>9</sub>)<sub>2</sub>]<sub>3</sub> where (x+y+z=5.3)**

10 A total of 100 grams (MW=581, 0.165 moles) of HN(SO<sub>2</sub>C<sub>4</sub>F<sub>9</sub>)<sub>2</sub> which was 96% active and 4% water, was dissolved in 175 grams of methyl t-butyl ether in a 1 liter flask fitted with and overhead stirrer, thermocouple, and addition funnel. While stirring 49 grams of JEFFAMINE™ T-403 (MW 440, 0.11 moles), available from Huntsman Corporation, Salt Lake City, UT., was added to the batch at 70°C over a 30 minute period.

15 The batch was stirred for an additional 15 minutes and the pH was measured to be in the range of 7 to 8. The batch set point was set at 70°C and fitted with an overhead distillation apparatus. The methyl t-butyl ether was stripped at atmospheric pressure until the pot temperature reached 80°C. Residual solvent and water were stripped to the receiver until the vacuum reached 13 mm Hg (1.7 kPa). The batch was held at 70°C and 13 mm Hg (1.7

20 kPa) for an hour. The amber very thick liquid was poured out into jars and weighed. A total of 116 grams of material was isolated.

Table 1 details the surface energy versus concentration profile for this material along with comparative perfluoroalkanesulfonate materials (DBI)3T-403.

Figure 5 shown previously is the same data shown graphically.

25

Table 1

	0 ppm	10 ppm	100 ppm	1000ppm
C <sub>8</sub> F <sub>17</sub> SO <sub>3</sub> K - comparative	72	67.68	54.09	33.17
C <sub>4</sub> F <sub>9</sub> SO <sub>3</sub> K - comparative	72	70	67.5	53
C <sub>4</sub> F <sub>9</sub> SO <sub>2</sub> NKSO <sub>2</sub> C <sub>4</sub> F <sub>9</sub>	72	61.85	41.61	34.02
(DBI)2 JEFFAMINE™ ED600	72	57.4	40.7	32.7
Example 6	72	34.3	33.4	28.6

**Example 7. Synthesis of  $Mg^{+2}[N(SO_2C_4F_9)_2]_2$** 

A total of 36 grams of  $HN(SO_2C_4F_9)_2$  from Example 2 was dissolved in 36 grams of water. The pH of the solution was in the range of 0 to 1. A total of 2.4 grams of magnesium carbonate (Mallinckrodt, St. Louis, MO.) was added with stirring. The pH was measured to be about 6. The flask was then cooled to room temperature. The white solid precipitate in the flask was filtered and washed out with repeated water washings and then oven dried to give 13.1 grams of the desired dry potassium salt. Results of surface tension measurements in the water (dyne/cm) are shown in Table 2.

Table 2

	0 ppm	200 ppm	450 ppm	960 ppm	1300 ppm	1700 ppm	2600 ppm
Mg (DBI) <sub>2</sub>	71.0	46.6	40.2	35.0	32.0	29.0	26.3
DBI-NH <sub>4</sub>	71.0	48.6	44.1	40.1	38.7	35.9	31.5
DBI-Li	71.0	53.2	48.1	42.8	41.5	39.1	36.0

Figure 6 show the data graphically and compares it with the ammonium and lithium salts of DBI.

**Example 8. Hydraulic Fluid**

A hydraulic fluid (adopted from WO93/25641; Example 1) containing an anti-erosion agent of the present invention ( $K[N(SO_2C_4F_9)_2]$ ) is prepared according to the composition described in Table 3.

Table 3

Material	%	Availability
Tributyl Phosphate	49.0135	Aldrich Chemical Co. Milwaukee, WI
Dibutyl phenyl phosphate	26.34	Exchange Chemical Inc Center Ossipee, NH
Methacrylate Ester Viscosity Index Improver (PA6477, 45.3% solids in tributyl phosphate)	16.56	Rohm & Haas, Philadelphia, PA
3,4 Epoxycyclohexane Carboxylate	6.3	Described in US Patent 3,723,320
K[N(SO <sub>2</sub> C <sub>4</sub> F <sub>9</sub> ) <sub>2</sub> ]	0.05	Example 4
Benzotriazole type Copper Corrosion Inhibitor P57068, 50% active EXI 663	0.05	Baker Petrolite, Sugarland, TX
Iron Corrosion Inhibitor (90-31001 50% active)	0.05	Baker Petrolite, Sugarland, TX
Soluble Dye	0.001	
Potassium Phenoxide	0.035	Organometallics, Inc East Hampstead, NH
Bis(3,5 di- <i>tert</i> -butyl-4-hydroxyphenyl) methane (Ethanox 702)	0.90	Albemarle Corporation, Baton Rouge, LA
Di( <i>p</i> -octylphenyl) amine (Vanlube <sup>TM</sup> 81 )	0.45	R. T. Vanderbilt, Norwalk, Connecticut
2,6,-di- <i>tert</i> -butyl-4-methylphenol	0.25	Aldrich Chemical Co. Milwaukee, WI
Antifoam DC 200	0.0005	Dow Corning, Midland, MI

### **Example 9. Conductivity of Potassium salts in Tributylphosphate**

5            This example illustrates the improved conductivity provided by potassium bis(perfluorobutanesulfonyl)imide versus the known art and erosion additives (PBSK and FC-98) when dissolved in a typical aircraft hydraulic base fluid, tributylphosphate.

10           Four tributylphosphate samples, with or without dissolved anti-erosion additives, measured for DC conductivity. The four samples were neat tributyl phosphate (control), tributyl phosphate with 3000 ppm FC-98, tributyl phosphate with 3000 ppm PBSK, and tributyl phosphate with 3000 ppm potassium bis(perfluorobutanesulfonyl)imide (DBIK).

            Conductivity was measured using an Orion Model 122 DC Conductivity meter with 4-electrode conductivity probe (epoxy body, carbon electrodes, model 012210) with temperature sensing and compensation available from ThermoOrion, Beverly, MA.

The conductivity probe was carefully cleaned with EM Science OMNISOLV™ grade methanol, dried in a clean nitrogen stream, and allowed to equilibrate back to ambient temperature between samples.

5

Table 4

Sample	Observed Conductivity (uS/cm)
Tributyl Phosphate (control sample)	0.1 uS/cm @ 21.6°C
Tributyl Phosphate with 3000 ppm FC-98 comparative	3.2 uS/cm @ 21.9°C
Tributyl Phosphate with 3000 ppm PBSK comparative	3.5 uS/cm @ 21.6°C
Tributyl Phosphate with 3000 ppm DBIK	13.8 uS/cm @ 21.7°C

When the conductivity of the same samples were measured by total AC impedance, the results were in agreement with these values.

10

**Example 10.**

Surface tension measurements were obtained as described above with the exception that the measurements were obtained in tributyl phosphate.

15

Table 5

Material	Surface Tension @ 2000 ppm (dyne/cm)
Tributyl Phosphate - comparative	28.37
Mg(C <sub>8</sub> F <sub>17</sub> SO <sub>3</sub> ) <sub>2</sub> - comparative	27.36
FC-98 - comparative	26.94
K[N(SO <sub>2</sub> C <sub>4</sub> F <sub>9</sub> ) <sub>2</sub> ]	27.34
FC-95 - comparative	26.96
Mg[N(SO <sub>2</sub> C <sub>4</sub> F <sub>9</sub> ) <sub>2</sub> ] <sub>2</sub>	27.04
Ca(C <sub>8</sub> F <sub>17</sub> SO <sub>3</sub> ) <sub>2</sub> - comparative	26.15
Mg(SO <sub>3</sub> C <sub>4</sub> F <sub>9</sub> ) <sub>2</sub> · 6H <sub>2</sub> O - comparative	26.93
K(SO <sub>3</sub> C <sub>4</sub> F <sub>9</sub> ) - comparative	27.32

**Example 11. Bioelimination Study with Perfluorobutanesulfonate**

Comparative study of potassium perfluorobutanesulfonate (using a dose level of 30 mg/kg body weight/day), potassium perfluorohexanesulfonate (using a dose level of 10 mg/kg body weight/day), and potassium perfluorooctanesulfonate (using a dose level of 3 mg/kg body weight/day). The amounts of fluorochemical sulfonate found in the male rat liver tissue samples are shown in Table 6.

Table 6

Sulfonate	Amount (ppm) of Sulfonate					
	Day 1	Day 1N*	Day 14	Day 14N*	Day 28	Day 28N*
$C_8F_{17}SO_3^-$	419 $\pm$ 86	419	309 $\pm$ 34	309	237 $\pm$ 25	237
$C_6F_{13}SO_3^-$	327 $\pm$ 52	98	61.9 $\pm$ 11.7	19	36.3 $\pm$ 7.4	11
$C_4F_9SO_3^-$	3.09 $\pm$ 1.58	0.31	0.126 $\pm$ 0.084	0.0126	0.025 $\pm$ 0.015	0.0025

\* Normalized to a feeding level of 3 mg/kg body weight per day.

10

The results in Table 6 show unexpectedly fast and effective elimination of  $C_4F_9SO_3^-$  as demonstrated by the extremely small amounts found, particularly relative to  $C_6F_{13}SO_3^-$  and  $C_8F_{17}SO_3^-$ . Immediately following completion of feeding,  $C_6F_{13}SO_3^-$  was a factor of 1.3 lower than  $C_8F_{17}SO_3^-$ , but  $C_4F_9SO_3^-$  was more than a factor of 100 lower than  $C_6F_{13}SO_3^-$ .

15

At 28 days following completion of feeding,  $C_6F_{13}SO_3^-$  was a factor of 6.5 lower than  $C_8F_{17}SO_3^-$ , but  $C_4F_9SO_3^-$  was more than a factor of 1400 lower than  $C_6F_{13}SO_3^-$ . After normalization to the same feeding levels, at 28 days following completion of feeding,  $C_6F_{13}SO_3^-$  was a factor of 21.5 lower than  $C_8F_{17}SO_3^-$ , but  $C_4F_9SO_3^-$  was a factor of 4400 lower than  $C_6F_{13}SO_3^-$ .

20

60557-7008

CLAIMS:

1. A method of reducing the surface tension of a solution comprising:

i) providing an aqueous solution wherein said aqueous solution is selected from the group consisting of:

(a) ammonium fluoride and hydrogen fluoride solution;

(b) tetramethyl ammonium hydroxide solution;

(c) an acid copper plating solution comprising copper sulfate and sulfuric acid;

(d) a CMP slurry comprising abrasive particles selected from the group consisting of alumina, silica, and cerium; oxidant, etchant, and corrosion inhibitors;

(e) a wafer cleaning solution comprising one or more of  $H_2O_2$ ,  $O_3$ ,  $H_2SO_4$ ,  $NH_4OH$ , or  $HCl$ ;

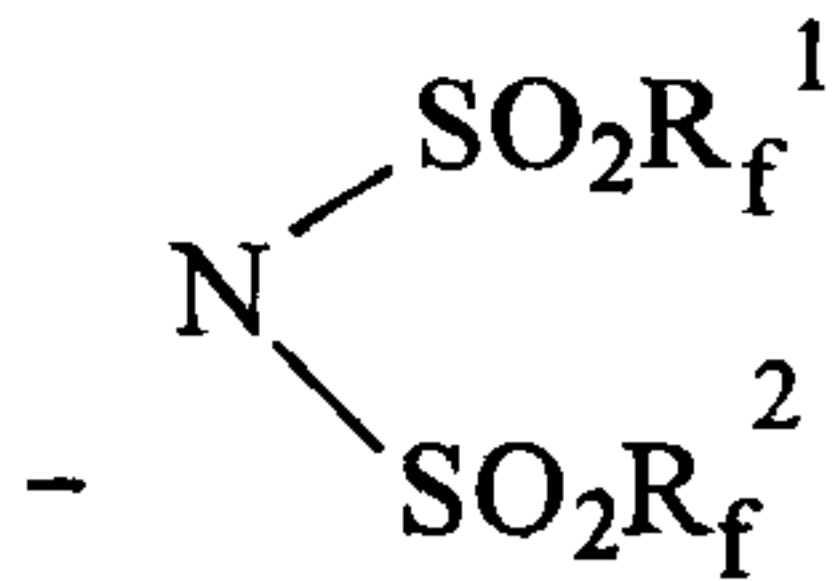
(f) sodium, ammonium, or potassium hydroxide solution, quaternary ammonium hydroxides, ethylenediamine, or ethanolamine solutions; and

(g) chromium trioxide, other chromium (VI) ions, and sulfuric acid; and

ii) adding to said solution a surface active agent comprising a bis(perfluoroalkanesulfonyl)imide or its salts.

2. The method of reducing the surface tension of a solution according to claim 1, wherein said bis(perfluoroalkanesulfonyl)imide is represented by the formula:

60557-7008

M<sup>+</sup>

where  $\text{R}_f^1$  and  $\text{R}_f^2$  are independently a perfluoroalkyl group comprising from 1 to 12 carbon atoms, and M is H or an inorganic or organic cation.

3. The method of reducing the surface tension of a solution according to claim 1, wherein said bis(perfluoroalkanesulfonyl)imide is  
 10 bis(perfluorobutanesulfonyl)imide.

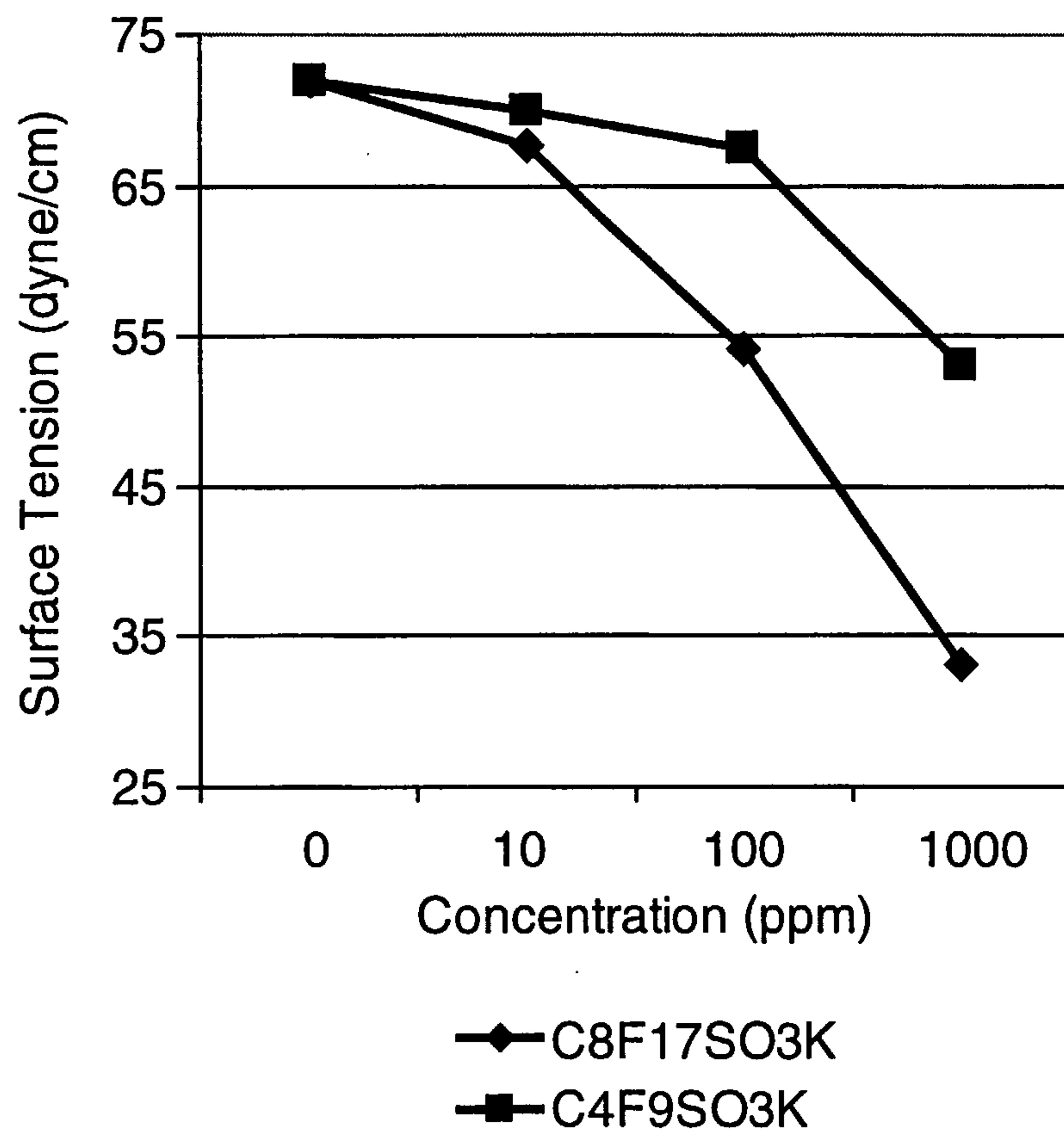
4. The method of reducing the surface tension of a solution according to claim 1, wherein said bis(perfluoroalkanesulfonyl)imide salt comprises a cation selected from the group consisting of alkali metal cations, alkaline earth metal cations,  $\text{H}^+$ ,  $\text{H}_3\text{O}^+$ ,  $\text{NH}_4^+$ ,  $\text{Cu}^{2+}$ ,  $\text{Zn}^{2+}$ , and  
 15 organo-nitrogen, organo-oxygen, and organo-phosphorous onium cations.

5. The method of reducing the surface tension of a solution according to claim 4, wherein said cation is  
 20 selected from the group consisting of  $\text{H}^+$ ,  $\text{NH}_4^+$ ,  $\text{H}_3\text{O}^+$ ,  $\text{Na}^+$ ,  $\text{K}^+$ ,  $\text{Li}^+$ ,  $\text{Mg}^{2+}$ ,  $\text{Ca}^{2+}$ ,  $\text{Zn}^{2+}$ , and  $\text{Cu}^{2+}$ .

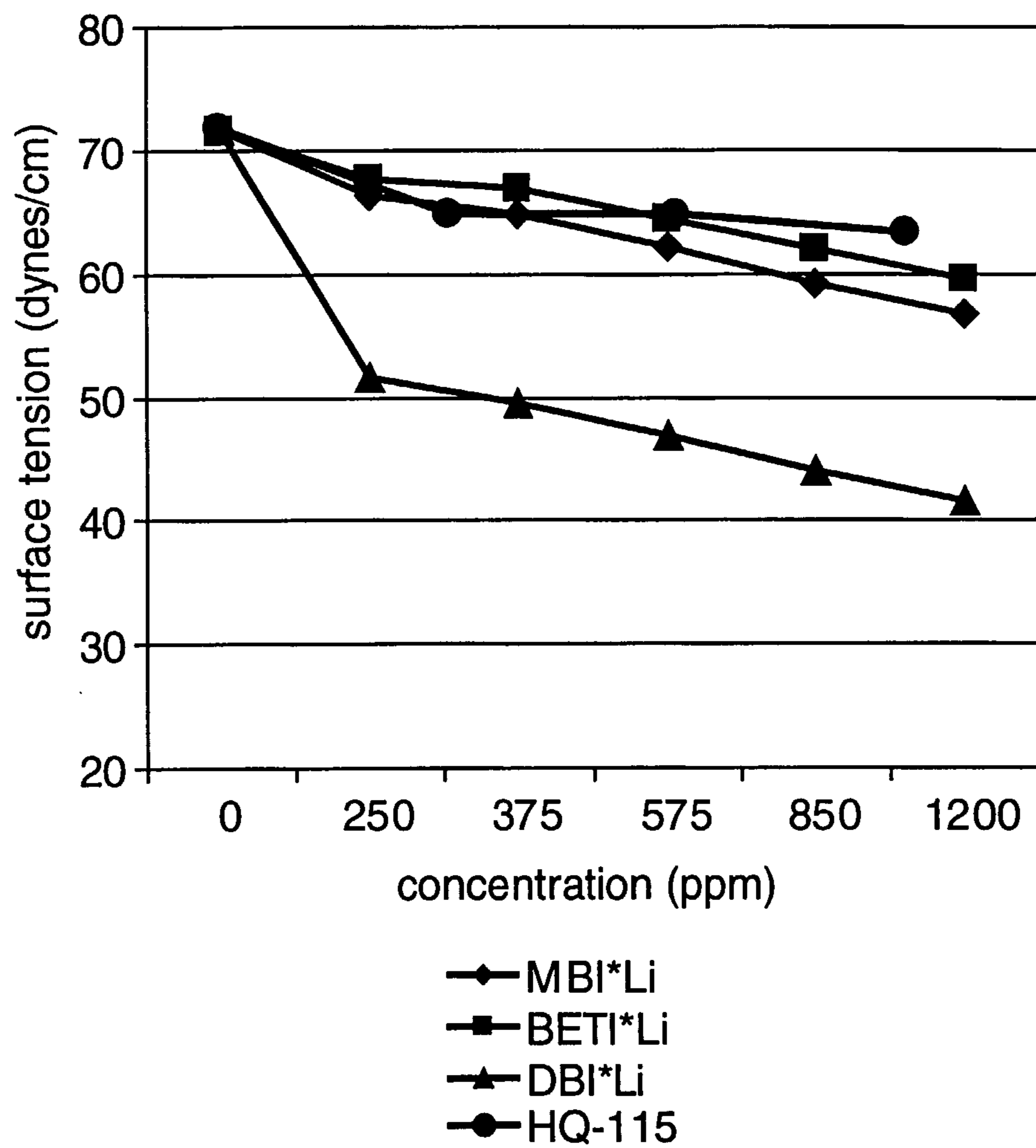
SMART & BIGGAR  
 OTTAWA, CANADA

PATENT AGENTS

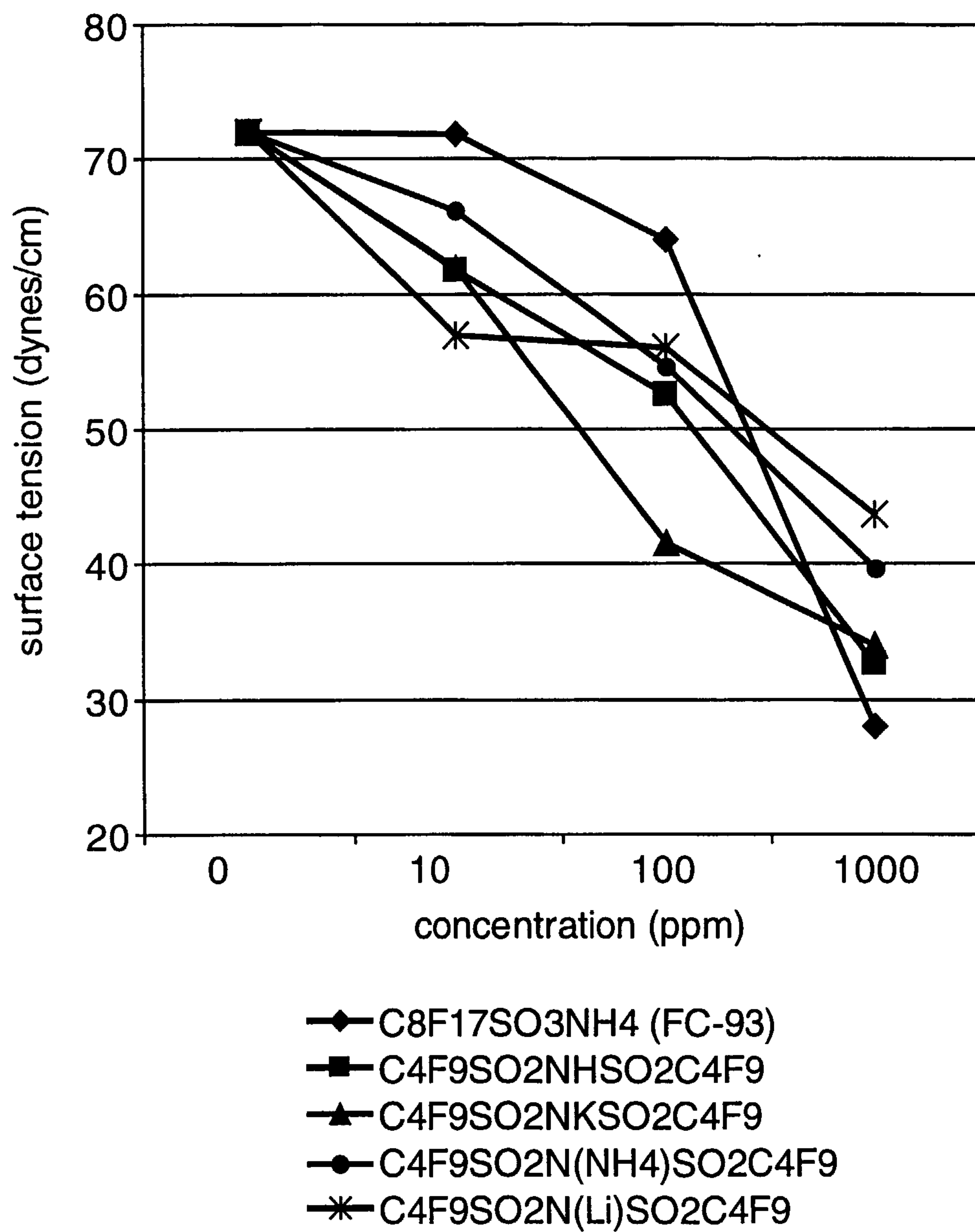
1/6

*Fig. 1*

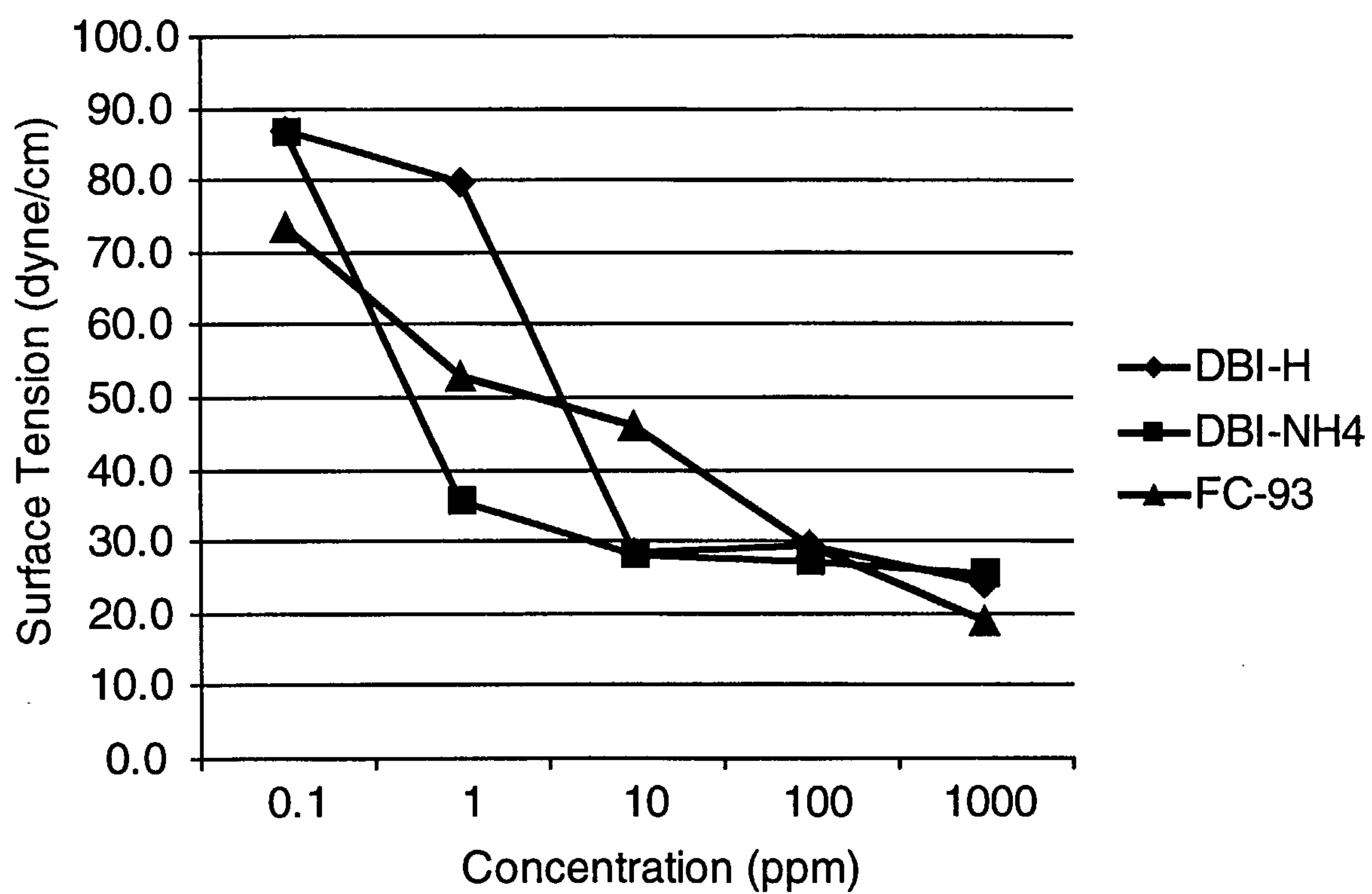
2/6

*Fig. 2*

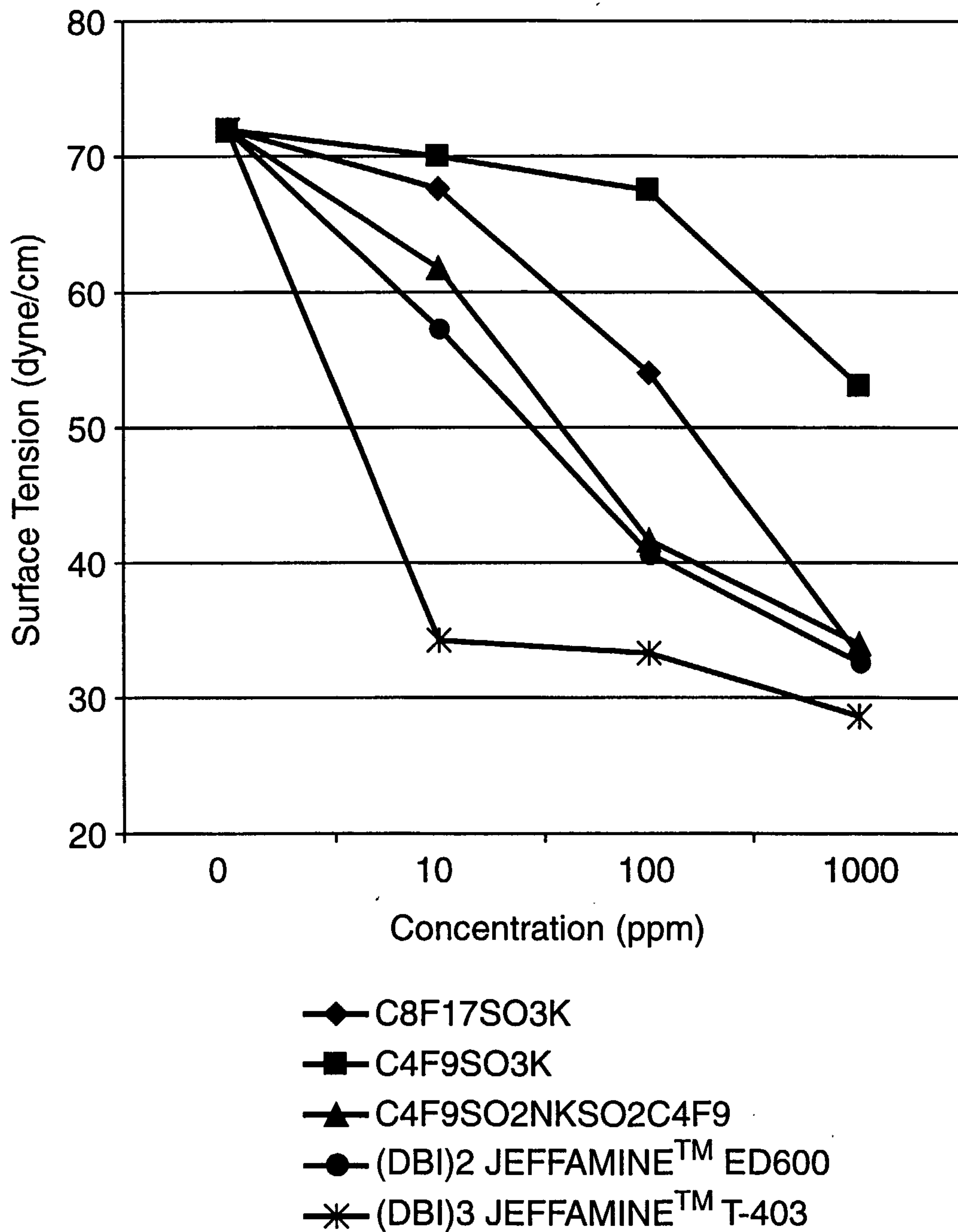
3/6

*Fig. 3*

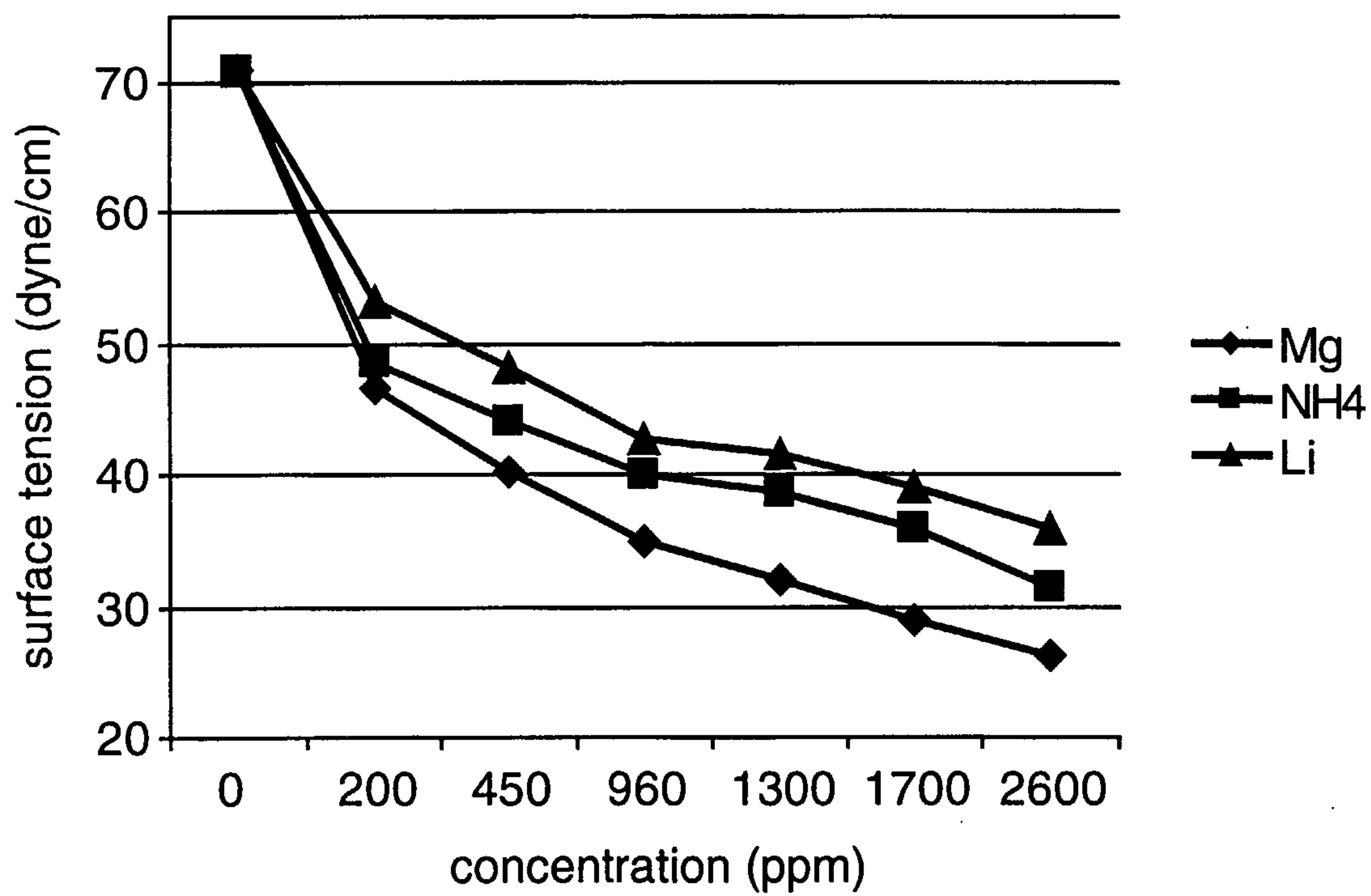
4/6

*Fig. 4*

5/6

*Fig. 5*

6/6

*Fig. 6*

